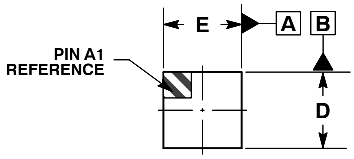
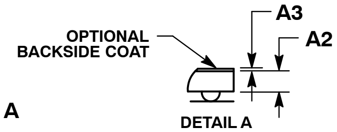
SCALE 4:1

WLCSP4, 0.84x0.86
CASE 567DC
ISSUE F

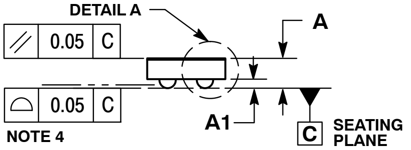
DATE 14 Jul 2016



TOP VIEW

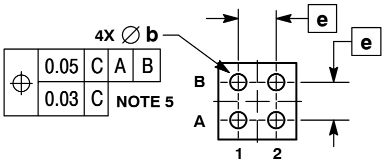


DETAIL A



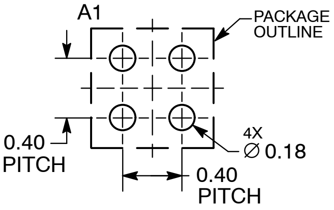
NOTE 3

SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



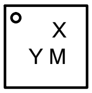
DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	---	---	0.38
A1	0.08	0.10	0.12
A2	0.23 REF		
A3	0.025 REF		
b	0.16	0.18	0.20
D	0.82	0.84	0.86
E	0.84	0.86	0.88
e	0.40 BSC		

GENERIC MARKING DIAGRAM*



X = Specific Device Code
Y = Year
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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